Form PTO-1595 (Rev. 03-11) <u>DMB N</u> o. 065 1-0027 (exp. 03/31/2015)	U.S. DEPARTMENT OF COMMER United States Patent and Trademark Of
RECORDATION FOI	
	e record the attached documents or the new address(es) below.
1. Name of conveying party(les):	2. Name and address of receiving party(ies)
Masaki \$akurai	Name: Sony Corporation
	Internal Address:
Additional name(s) of conveying party(les) attached?	Street Address:
3. Nature of conveyance/Execution Date(s):	1-7-1 Konan, Minato-ku
Execution Date(s): July 14, 2006	Tokyo 108-0075
x Assignment Merger Change of Name	JAPAN
Security Agreement Joint Research Agreement	City:
Government Interest Assignment	
Executive Order 9424, Confirmatory License	State:
	Country: Zip: Additional name(s) & address(es) Ves V No
Other	Additional name(s) & address(es)
13/955,410	
Additional numbers attached	
 Name and address to whom correspondence concerning document should be mailed: 	6. Total number of applications and patents involved:
Name: Davy E. Zoneraich LERNER. DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
Internal Address: Atty. Dkt.; SONYJP 3.0-583 CON CON II CON CON	
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account
	Enclosed
	None required (government interest not affecting title
City: Westfield	8. Payment Information
State: NJ Zip: 07090	
Phone Number: 908-654-5000	
Fax Number: 908-654-7866	Deposit Account Number 12-1095
Email Address:	Authorized User Name Davy E. Zoneraich
9. Signature:	August 1, 2013
Signature	Date
Davy E. Zonerstich - 37,267 Name of Person Signing	Total number of pages including cover 3 sheet, attachments, and documente.

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	ASSIGNMENT	Docket Number ; SÖNYJP 3.0-583 Sony Ref. No. ; S06P0571US00	
ole inveator (i nd useful limp	if only one name is listed below) or a joint i	or, residing at the address stated next to my name, am a inventor (if plural names are listed below) of certain new	
	IMAGE CAPTURING DEVIC	E AND ACTIVATION METHOD THEREFOR	
ior which appli text to my nam	ication for Letters Patent of the United States to and address;	s of America was executed by me on the date indicated	
n. to and unde	agawa-ku, Tokyo, Japan (hereinafter refere	Japanese corporation with offices at 7-35, Kitashinagawa anced as ASSIGNRE) is desirous of acquiring all interest is the invention and in, to and under any Letters Patent or be United States and in any and all foreign countries;	
as indicated be assigns, and ic any divisions s	deration, the receipt and sufficiency of which show, by these presents do hereby assign, so gal representatives, my entire right, title and	of the sum of One Dollar (\$ 1.00), and other good and the are hereby acknowledged, I, as a sole or joint inventor ell and transfer unto the said ASSIGNEE, its successors, i interest in the said invention, said application, including	
rights under the Relating to Pastates of Ame applications for authorize and r	which may be granted for said invention, s the International Convention for the Protec- tients, Designs and Industrial Models, and arice adheres, and to any other benefits ac ar palents or securing of patents in the Ur	and all Letters Patent of the United States, and countries and in and to any and all priority rights and/or convention any other international agreements to which the United erving or to accrue to me with respect to the filing of nited States and countries foreign thereto, and I hereby the said United States Letters Patent to said ASSIGNEE,	
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rights under the Relating to Pa States of Ame applications for authorize and it as the assignments for representatives said invention, States and court increases and court increases and court facts and there foreign countr litigation related made or chitere	which may be granted for said invention, s he international Convention for the Protec- tents, Designs and Industrial Models, and rice adheres, and to any other benefits ac or patents or securing of patents in the Un request the Commissioner of Patents to issue of the whole right, title and interest thereto; And I further agree to execute all necess in favor of ASSIGNEE or its designet, any from time-to-time present to me and modifications, and improvements in said intries foreign thereto; And I further agree to properly execu- desirable and lawfol papers for application patent, and or, for obtaining any relasue or invention, as the ASSIGNEE thereof shall her And I further agree that ASSIGNEE will biments relating to said application, said in- ics as may be known and accessible to me ad thereto; And I hereby covenant that no assignment into which would conflict with this assign And I hereby suthorize and request my mber and filing date of this application in the	and in and to any and all priority rights and/or convention any other international agreements to which the United cruing or to accrue to me with respect to the filing of nited States and countries foreign thereto, and I hereby the said United States Letters Patent to said ASSIGNEE, sary or desirable and lawful future documents, including as ASSIGNEE or its successors, assigns and legal without further remuneration, in order to perfect title in invention, applications and Letters Patent of the United reissues of any Letters Patent which may be granted for reafter require and prepare at its own expense; , upon its request, be provided promptly with all pertinent vention and said Letters Patent and legal equivalents in c and will testify as to the same in any interference or east, sale, agreement or encumbrance has been or will be	

former PTC/SB/15 (05/01)

	Docket Number ; SONYJF 3.0-583 Sony Ref No.: SDBP0571US00
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Name of First or Sole Inventor	Execution Date of U.S. Patent Application
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Tokyo, Japan Residence of First or Sole Inventor	****
Masahi Sakurai	July 14, 2006 Date of this Assignment
Signature of First or Sole Inventor	Date of this Assignment
Name of Second Joint Inventor	Execution Date of U.S. Patent Application
Residence of Second Joint Inventor	• •
Signature of Second Joint Inventor	Date of this Assignment
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Name of Third Joint Inventor	Execution Date of U.S. Patent Application
Residence of Third Joint Inventor	
Signature of Third Joint Inventor	Date of this Assignment
Name of Fourth Joint Inventor	Execution Date of U.S. Patent Application
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RECORDED: 08/01/2013